

Preliminary Spec.

Some of contents are subject to change without notice.

MITSUBISHI LSIs

MH16M40AJD -6 Proto-2

FAST PAGE MODE (16,777,216-WORD BY 40-BIT) DYNAMIC RAM

DESCRIPTION

The MH16M40AJD is a 16M word by 40-bit dynamic RAM module and consists of 10 industry standard 16M X 4 dynamic RAMs in a TSOP package.

The ICs are mounted on both sides of two small PC boards (Ceracom) with the flash gold plating and form a convenient 69-pin WDIP package.

FEATURES

Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
MH16M40AJD-6	60	15	30	15	110	2500

- Utilizes industry standard 16M X 4 DRAMs in TSOP package
- Low stand-by power dissipation
13mW (Max) CMOS Input level
- Low operating power dissipation
MH16M40AJD - 6 3242 mW (Max)
- Fast-page mode , Read-modify-write,RAS-only refresh
CAS before RAS refresh, Hidden refresh capabilities
- Early-write mode and OE to control output buffer impedance
- All inputs, output TTL compatible and low capacitance
- 4096 refresh cycles every 64ms (A0 - A12) (CbR only)
- Includes (0.22uF x 12) decoupling capacitors
- 5.0V ± 5% Vcc
- 3.3V Vdd by onboard mounted regulators
- TTL input converted to LVTTL by onboard mounted level shifters.

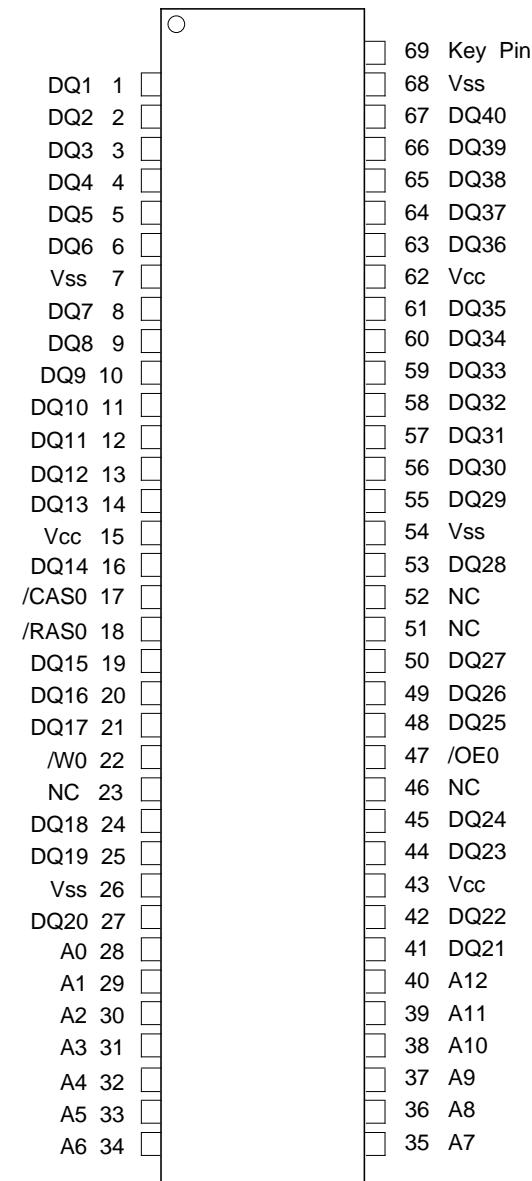
APPLICATION

Main memory unit for computers, Microcomputer memory,
Refresh memory for CRT

PIN DESCRIPTION

Pin Name	Function
A0-A12	Address Inputs
DQ1-DQ40	Data Inputs / Outputs
RAS 0	Row Address Strobe Input
CAS 0	Column Address Strobe Input
W 0	Write Control Input
OE 0	Output Enable Input
Vcc	Power Supply (+5V)
Vss	Ground (0V)

PIN CONFIGURATION (TOP VIEW)



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FUNCTION

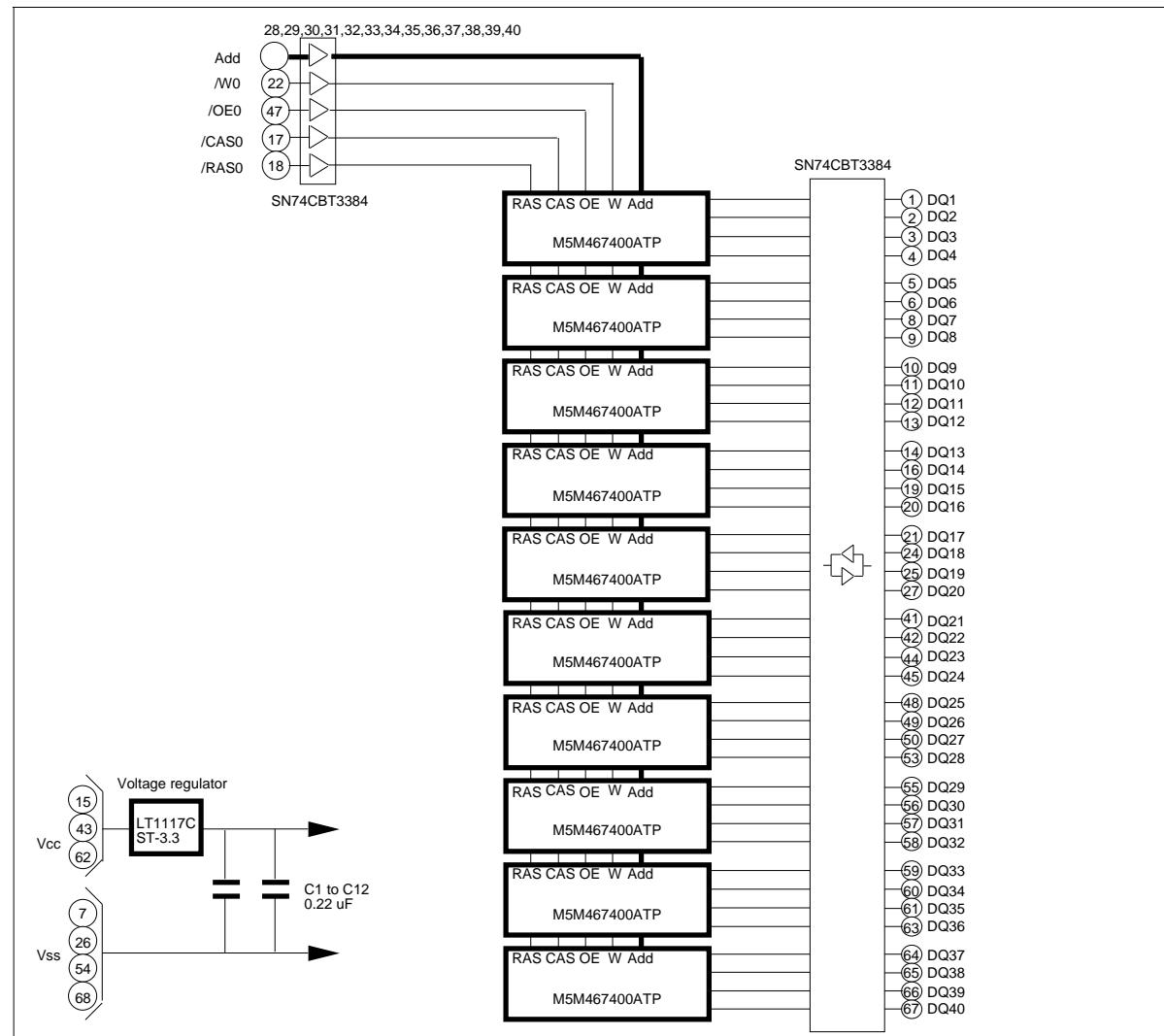
The MH16M40AJD provide, in addition to normal read, write, and read-modify-write operations,

a number of other functions, e.g., fast page mode, CAS before RAS refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs						Input/Output		Refresh	Remark
	RAS	CAS	W	OE	Row address	Column address	Input	Output		
Read	ACT	ACT	NAC	ACT	APD	APD	OPN	VLD	YES	
Write (Early write)	ACT	ACT	ACT	DNC	APD	APD	VLD	OPN	YES	
Write (Delayed write)	ACT	ACT	ACT	DNC	APD	APD	VLD	IVD	YES	
Read-modify-write	ACT	ACT	ACT	ACT	APD	APD	VLD	VLD	YES	
Hidden refresh	ACT	ACT	NAC	ACT	DNC	DNC	OPN	VLD	YES	
CAS before RAS refresh	ACT	ACT	NAC	DNC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : Invalid, APD : applied, OPN : open

BLOCK DIAGRAM

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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage	With respect to Vss	-0.5 ~ 7	V
VI	Input voltage		-0.5 ~ 6	V
V0	Output voltage		-0.5 ~ 6	V
IO	Output current		50	mA
Pd	Power dissipation	Ta=25 °C	15	W
Topr	Operating temperature		0 ~ 70	°C
Tstg	Storage temperature		-40 ~ 100	°C

RECOMMENDED OPERATING CONDITIONS (Ta=0 ~ 70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
Vcc	Supply voltage	4.75	5	5.25	V
Vss	Supply voltage	0	0	0	V
VIH	High-level input voltage, all inputs	2.0		5.5	V
VIL	Low-level input voltage, all inputs	-0.3		0.8	V

Note 1 : All voltage values are with respect to Vss

ELECTRICAL CHARACTERISTICS (Ta=0 ~ 70°C, Vcc=5V ± 5%, Vss=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
VOH	High-level output voltage	I _{OH} =-2mA	2.4		3.6	V
VOL	Low-level output voltage	I _{OL} =2mA	0		0.4	V
I _{OZ}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 3.6V	-10		10	uA
I _I	Input current	0V ≤ V _{IN} ≤ 5.25V, Other inputs pins=0V	-5		5	uA
I _{CC1(AV)}	Average supply current from Vcc operating (Note 3,4)	RAS, CAS cycling trc=twc=min. output open			900	mA
I _{CC2}	Supply current from Vcc , stand-by	RAS= CAS =V _{IH} , output open RAS= CAS ≥ V _{CC} -0.2			10	mA
I _{CC4(AV)}	Average supply current from Vcc Fast-Page-Mode (Note 3,4)	RAS=V _{IL} , CAS cycling tpc=min. output open			800	mA
I _{CC6(AV)}	Average supply current from Vcc CAS before RAS refresh mode (Note 3)	CAS before RAS refresh cycling trc=min. output open			1200	mA

Note 2: Current flowing into an IC is positive, out is negative.

3: Icc1 (AV), Icc4 (AV) and Icc6 (AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: Icc1 (AV) and Icc4 (AV) are dependent on output loading. Specified values are obtained with the output open.

CAPACITANCE (Ta=0 ~ 70°C , Vcc=5V ± 5%, Vss=0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _{I(A)}	Input capacitance, address inputs	Vi=Vss f=1MHz Vi=25mVrms			20	pF
C _{I(OE)}	Input capacitance, OE input				20	pF
C _{I(W)}	Input capacitance, write control input				20	pF
C _{I(RAS)}	Input capacitance, RAS input				20	pF
C _{I(CAS)}	Input capacitance, CAS input				20	pF
C _{I/O}	Input/Output capacitance, data ports				20	pF

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SWITCHING CHARACTERISTICS (Ta=0 ~ 70°C , Vcc=5V ± 5%, Vss=0V, unless otherwise noted , see notes 5,12,13)

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
tcAC	Access time from CAS (Note 6,7)		15	ns	
trAC	Access time from RAS (Note 6,8)		60	ns	
tAA	Column address access time (Note 6,9)		30	ns	
tCPA	Access time from CAS precharge (Note 6,10)		35	ns	
toEA	Access time from OE (Note 6)		15	ns	
tCLZ	Output low impedance time from CAS low (Note 6)	5		ns	
toFF	Output disable time after CAS high (Note 11)	0	15	ns	
toEZ	Output disable time after OE high (Note 11)	0	15	ns	

Note 5: An initial pause of 500 us is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing CAS before RAS).

Note the RAS may be cycled during the initial pause . And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 64 ms) of RAS inactivity before proper device operation is achieved.

6: Measured with a load circuit equivalent to 1TTL loads and 100pF. The reference levels for measuring of output signals are 2.0V(VOH) and 0.8V(VOL).

7: Assumes that trCD ≥ trCD(max) and tASC ≥ tASC(max).

8: Assumes that trCD ≤ trCD(max) and trAD ≤ trAD(max). If trCD or trAD is greater than the maximum recommended value shown in this table, trAC will increase by amount that trCD exceeds the value shown.

9: Assumes that trAD ≥ trAD(max) and tASC ≤ tASC(max).

10: Assumes that tCP ≤ tCP(max) and tASC ≥ tASC(max).

11: toFF(max) and toEZ (max) defines the time at which the output achieves the high impedance state ($I_{out} \leq I \pm 10 \text{ uA}$) and is not reference to V_{OH(min)} or V_{OL(max)}.

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write ,Refresh, and Fast-Page Mode Cycles)

(Ta=0 ~ 70°C , Vcc=5V ± 5%, Vss=0V, unless otherwise noted See notes 12,13)

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
tREF	Refresh cycle time		64	ms	
tRP	RAS high pulse width	40		ns	
trCD	Delay time, RAS low to CAS low (Note14)	20	45	ns	
tCRP	Delay time, CAS high to RAS low	10		ns	
tRPC	Delay time, RAS high to CAS low	0		ns	
tCPN	CAS high pulse width	10		ns	
trAD	Column address delay time from RAS low (Note15)	15	30	ns	
tASR	Row address setup time before RAS low	0		ns	
tASC	Column address setup time before CAS low (Note16)	0	10	ns	
tRAH	Row address hold time after RAS low	10		ns	
tCAH	Column address hold time after CAS low	15		ns	
tdZC	Delay time, data to CAS low (Note17)	0		ns	
tdZO	Delay time, data to OE low (Note17)	0		ns	
tcDD	Delay time, CAS high to data (Note18)	15		ns	
tODD	Delay time, OE high to data (Note18)	15		ns	
tr	Transition time (Note19)	1	50	ns	

Note 12: The timing requirements are assumed tr=5ns.

13: V_{IH(min)} and V_{IL(max)} are reference levels for measuring timing of input signals.

14: trCD(max) is specified as a reference point only. If trCD is less than trCD(max), access time is trAC. If trCD is greater than trCD(max), access time is controlled exclusively by tcAC or tAA. trCD(min) is specified as trCD(min)=tRAH(min)+2tIH+tASC(min).

15: trAD(max) is specified as a reference point only. If trAD ≥ trAD(max) and tASC ≤ tASC(max), access time is controlled exclusively by tAA.

16: tASC(max) is specified as a reference point only. If trCD ≥ trCD(max) and tASC ≥ tASC(max), access time is controlled exclusively by tcAC.

17: Either tdZC or tdZO must be satisfied.

18: Either tcDD or tODD must be satisfied.

19: tr is measured between V_{IH(min)} and V_{IL(max)}.

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Read and Refresh Cycles

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
t _{RC}	Read cycle time	110		ns	
t _{RAS}	RAS iow pulse width	60	10000	ns	
t _{CAS}	CAS iow pulse width	15	10000	ns	
t _{CSH}	CAS hold time after RAS iow	60		ns	
t _{RSH}	RAS hold time after CAS iow	15		ns	
t _{RCS}	Read Setup time after CAS high	0		ns	
t _{RCH}	Read hold time after CAS iow (Note 20)	0		ns	
t _{RRH}	Read hold time after RAS iow (Note 20)	10		ns	
t _{RAL}	Column address to RAS hold time	30		ns	
t _{OCH}	CAS hold time after OE iow	15		ns	
t _{ORH}	RAS hold time after OE iow	15		ns	

Note 20: Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.**Write Cycle (Early Write and Delayed Write)**

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
t _{WC}	Write cycle time	110		ns	
t _{RAS}	RAS iow pulse width	60	10000	ns	
t _{CAS}	CAS iow pulse width	15	10000	ns	
t _{CSH}	CAS hold time after RAS iow	60		ns	
t _{RSH}	RAS hold time after CAS iow	15		ns	
t _{WCS}	Write setup time before CAS low (Note 22)	0		ns	
t _{WCH}	Write hold time after CAS iow	10		ns	
t _{CWL}	CAS hold time after W iow	15		ns	
t _{RWL}	RAS hold time after W iow	15		ns	
t _{WP}	Write pulse width	10		ns	
t _{DS}	Data setup time before CAS iow or W iow	0		ns	
t _{DH}	Data hold time after CAS iow or W iow	10		ns	
t _{OEH}	OE hold time after W iow	15		ns	

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Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
trWC	Read write/read modify write cycle time (Note21)	150		ns	
trAS	RAS low pulse width	95	10000	ns	
tcaS	CAS low pulse width	50	10000	ns	
tcsH	CAS hold time after RAS low	95		ns	
trSH	RAS hold time after CAS low	50		ns	
trCS	Read setup time before CAS low	0		ns	
tcWD	Delay time, CAS low to W low (Note22)	30		ns	
trWD	Delay time, RAS low to W low (Note22)	75		ns	
tAWD	Delay time, address to W low (Note22)	45		ns	
tcWL	CAS hold time after W low	15		ns	
trWL	RAS hold time after W low	15		ns	
tWP	Write pulse width	10		ns	
tBS	Data setup time before W low	0		ns	
tDH	Data hold time after W low	10		ns	
toEH	OE hold time after W low	15		ns	

Note 21: trWC is specified as trWC(min)=tRAC(max)+tODD(min)+tRWL(min)+tRP(min)+4tr.

22: twcs, tcWD, trWD and tAWD and, tcpWD are specified as reference points only. If twcs ≥ twcs(min) the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If tcWD ≥ tcWD(min), trWD ≥ trWD(min), tAWD ≥ tAWD(min) and tcpWD ≥ tcpWD(min) (for fast page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition (delayed write) of the DQ (at access time and until CAS or OE goes back to Vih) is indeterminate.

Fast-Page Mode Cycle (Read, Early Write, Read -Write, Read-Modify-Write Cycle) (Note 23)

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
tPC	Fast page mode read/write cycle time	40		ns	
tPRWC	Fast page mode read write/read modify write cycle time	75		ns	
trAS	RAS low pulse width for read write cycle (Note24)	100	102400	ns	
tcp	CAS high pulse width (Note25)	10	15	ns	
tcpRH	RAS hold time after CAS precharge	35		ns	
tcpWD	Delay time, CAS precharge to W low (Note22)	35		ns	

Note 23: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

24: trAS(min) is specified as two cycles of CAS input are performed.

25: tCP(max) is specified as a reference point only. If tCP ≥ tCP(max), access time is controlled exclusively by tCAC.

CAS before RAS Refresh Cycle (Note 26)

Symbol	Parameter	Limits		Unit	
		-6			
		Min	Max		
tCSR	CAS setup time before RAS low	10		ns	
tCHR	CAS hold time after RAS low	10		ns	
tRSR	Read setup time before RAS low	10		ns	
tRHR	Read hold time after RAS low	10		ns	

Note 26: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

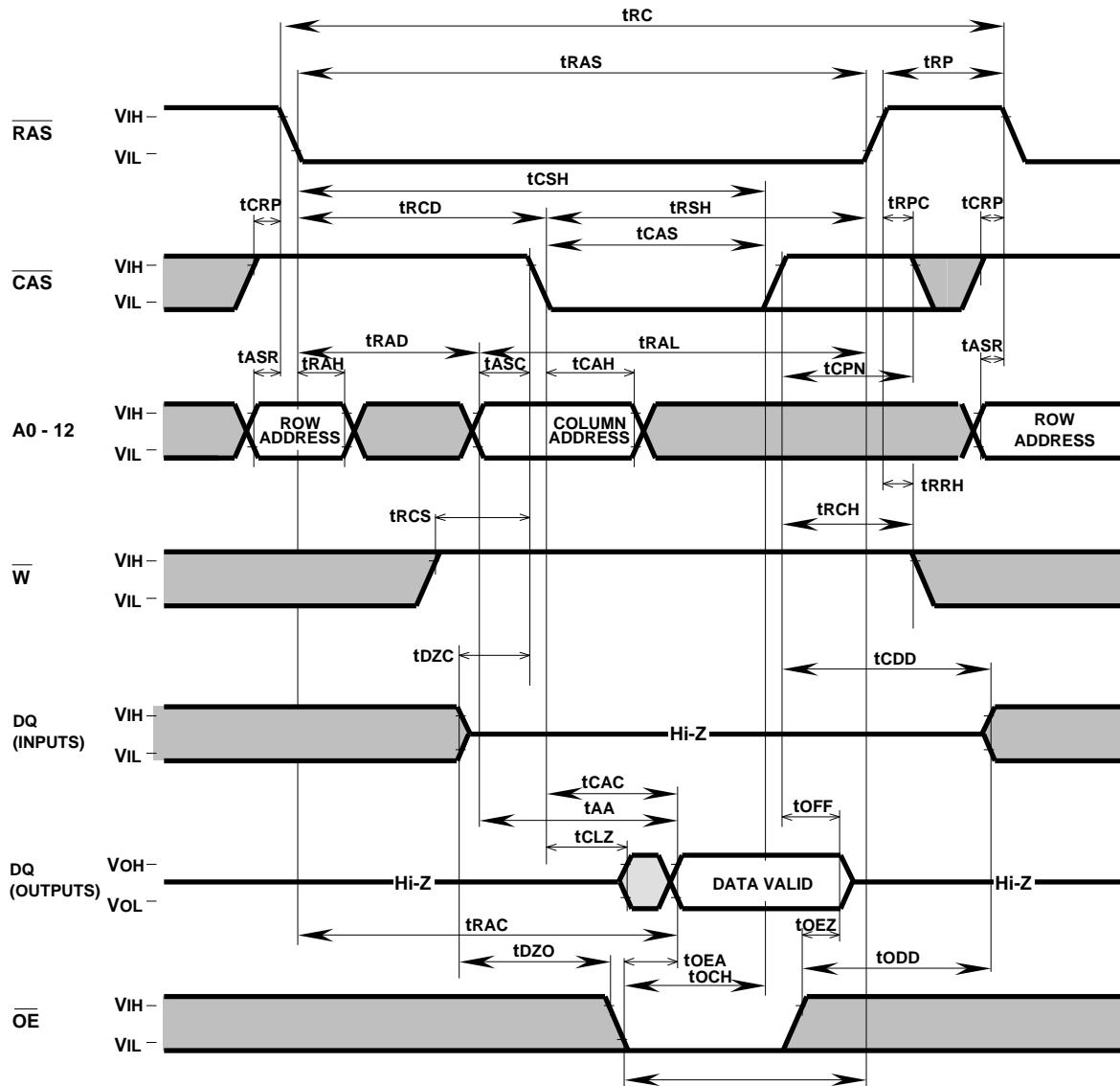
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Timing Diagrams (Note 27)

Read Cycle



Note 27



Indicates the don't care input.

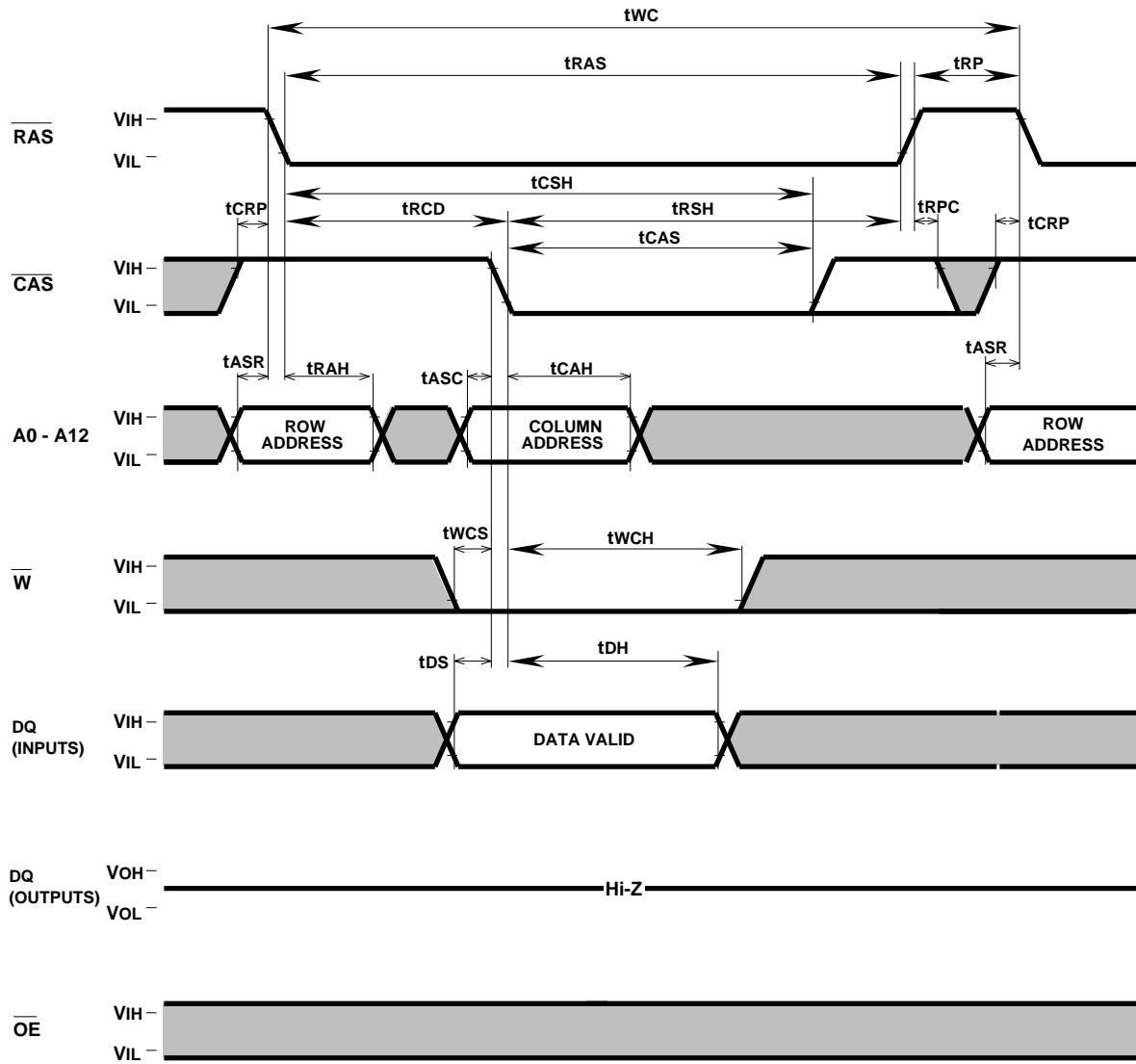
 $VIH(\min) \leq VIN \leq VIH(\max)$ or
 $VIL(\min) \leq VIN \leq VIL(\max)$

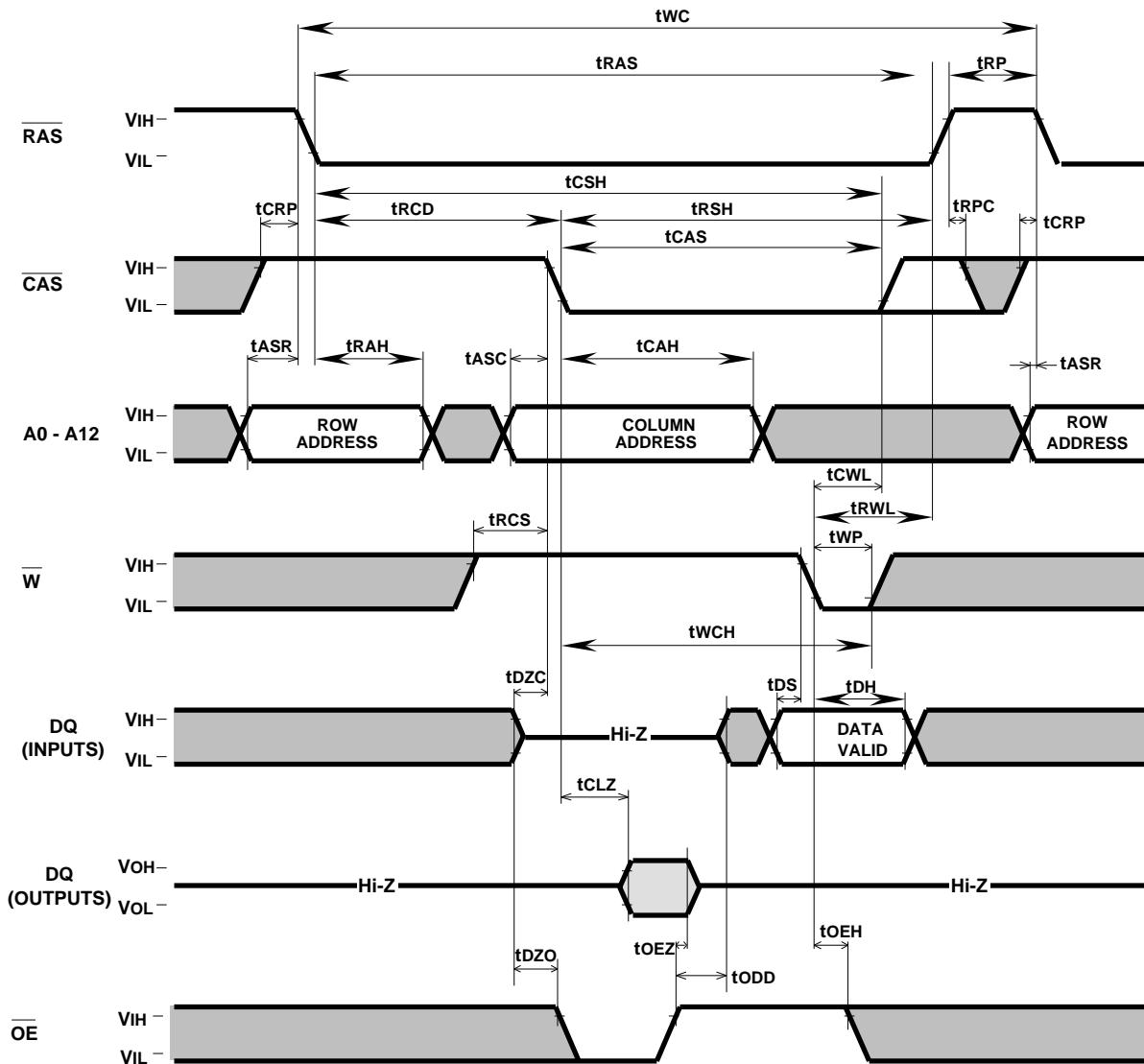
Indicates the invalid output.

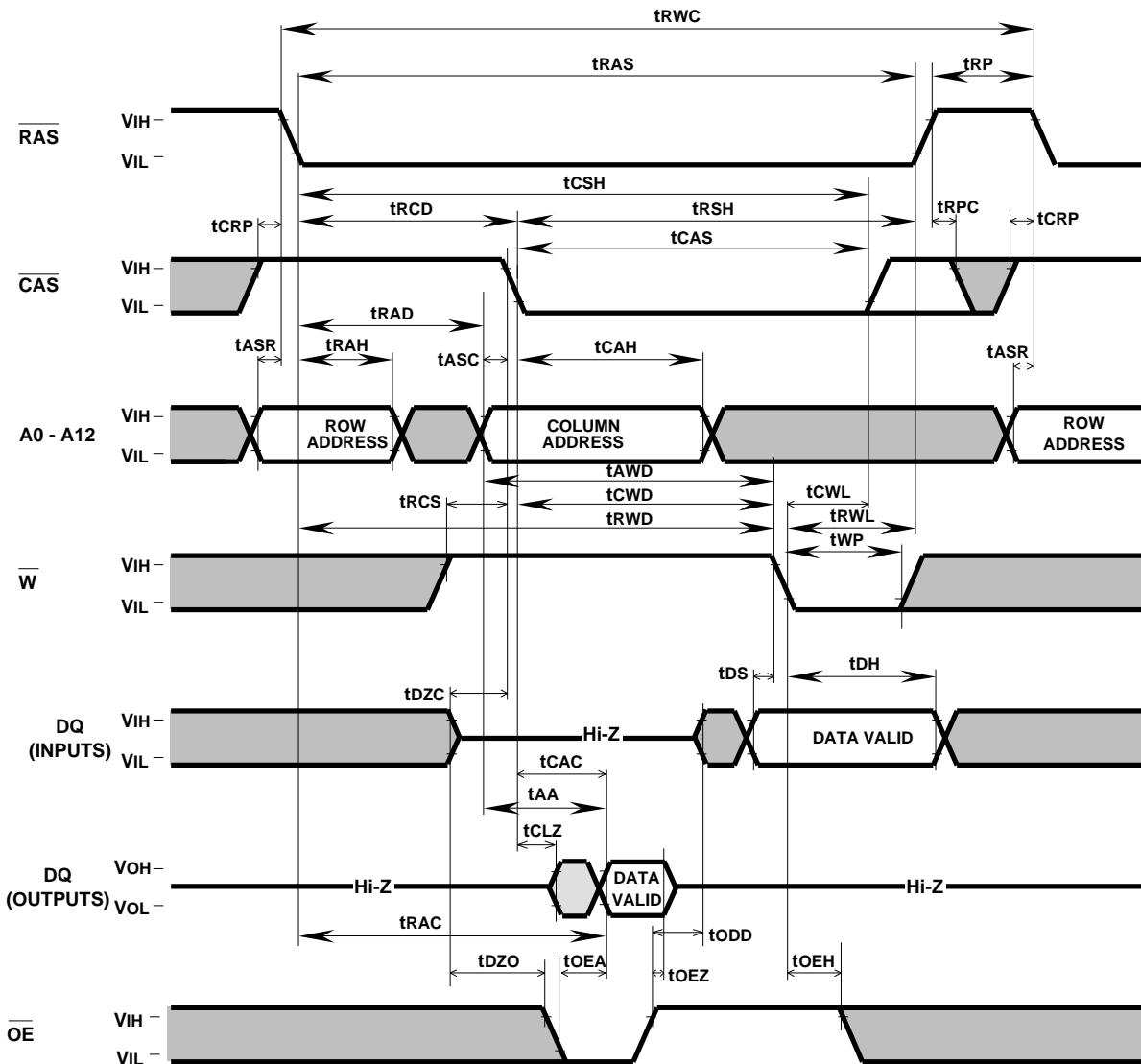
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Write Cycle (Early write)

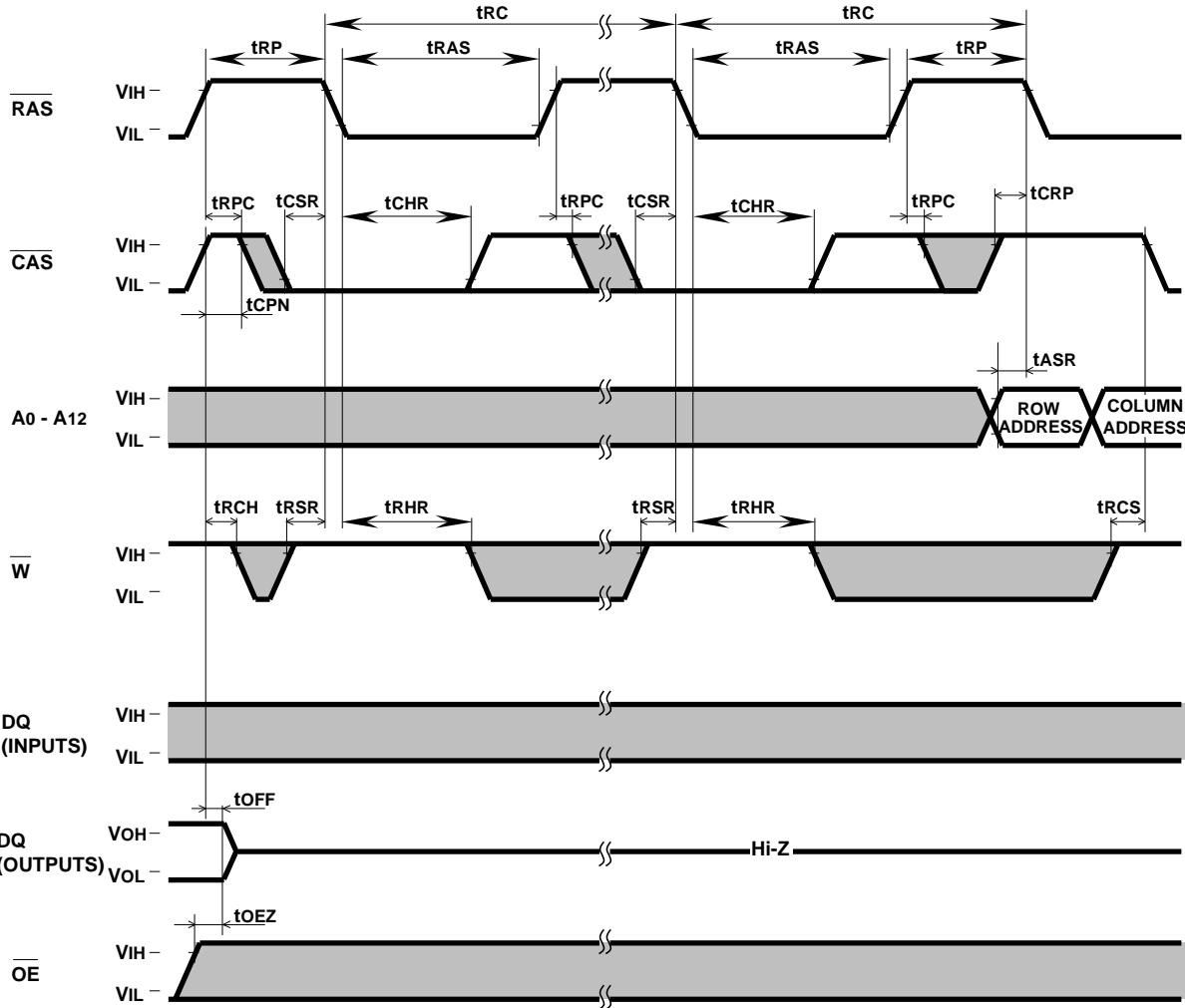
Write Cycle (Delayed write)

Read-Write, Read-Modify-Write Cycle

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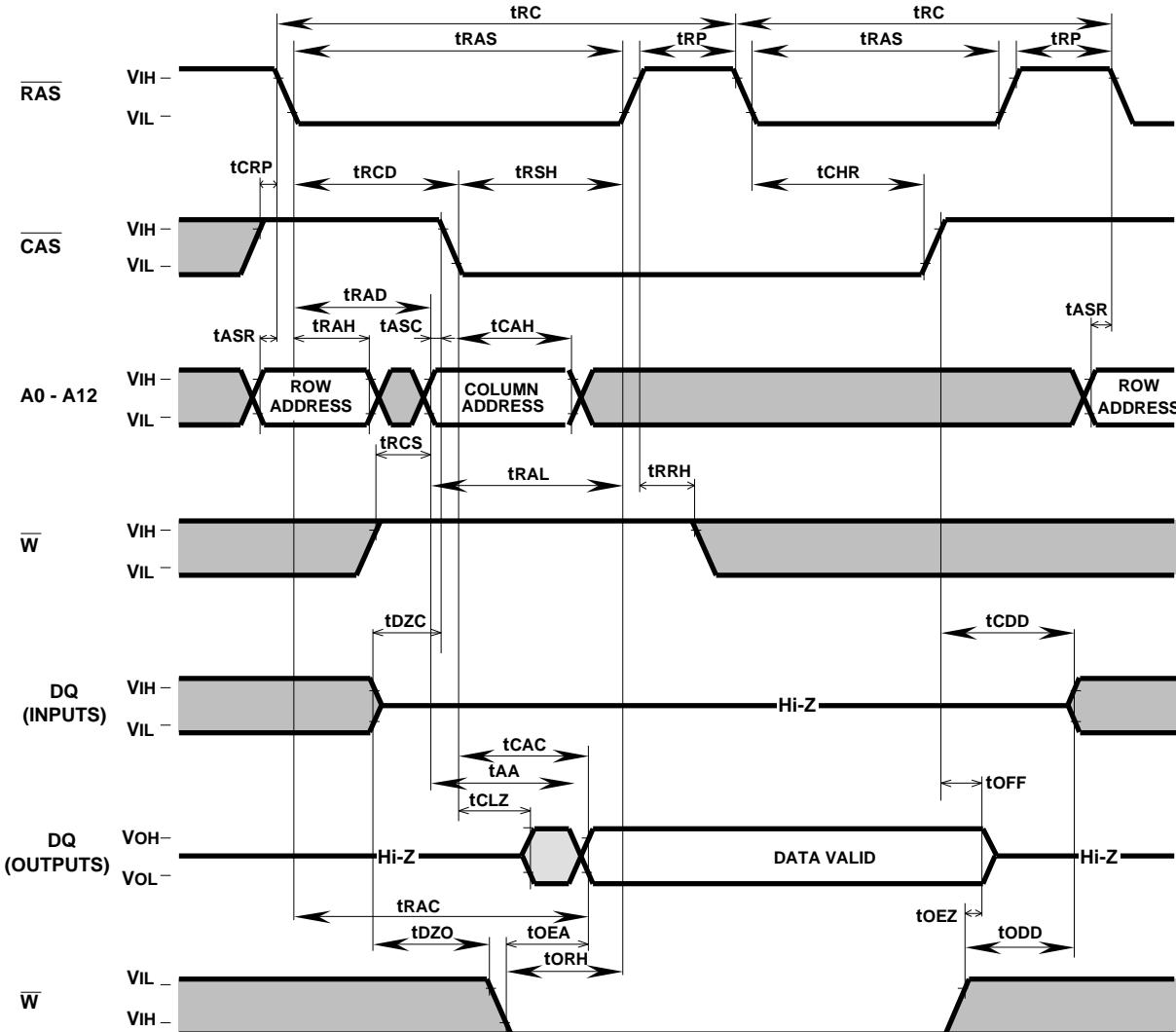
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CAS before RAS Refresh Cycle

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Hidden Refresh Cycle (Read) (Note 28)

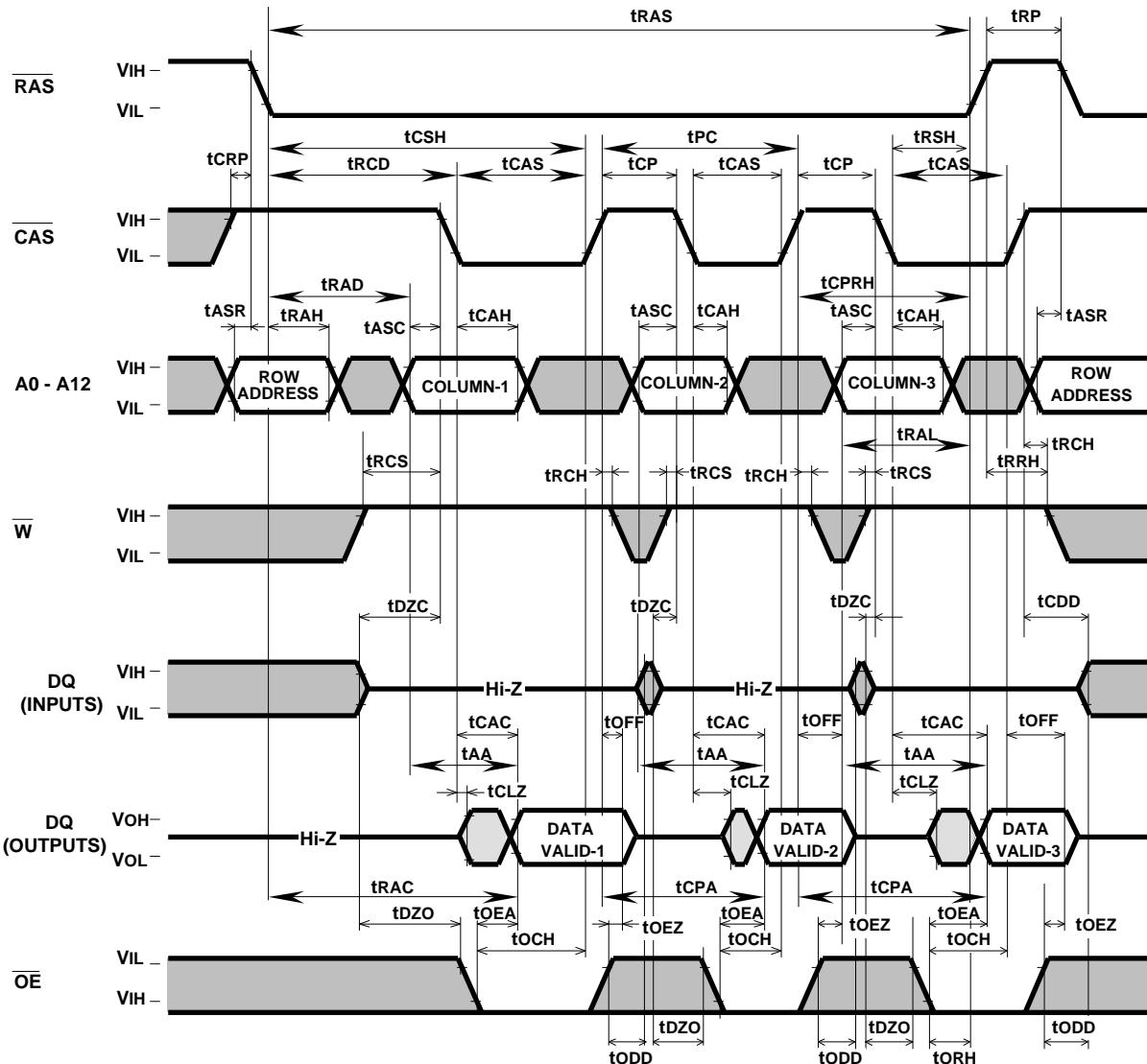
Note 28: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle.
 Timing requirements and output state are the same as that of each cycle shown above.

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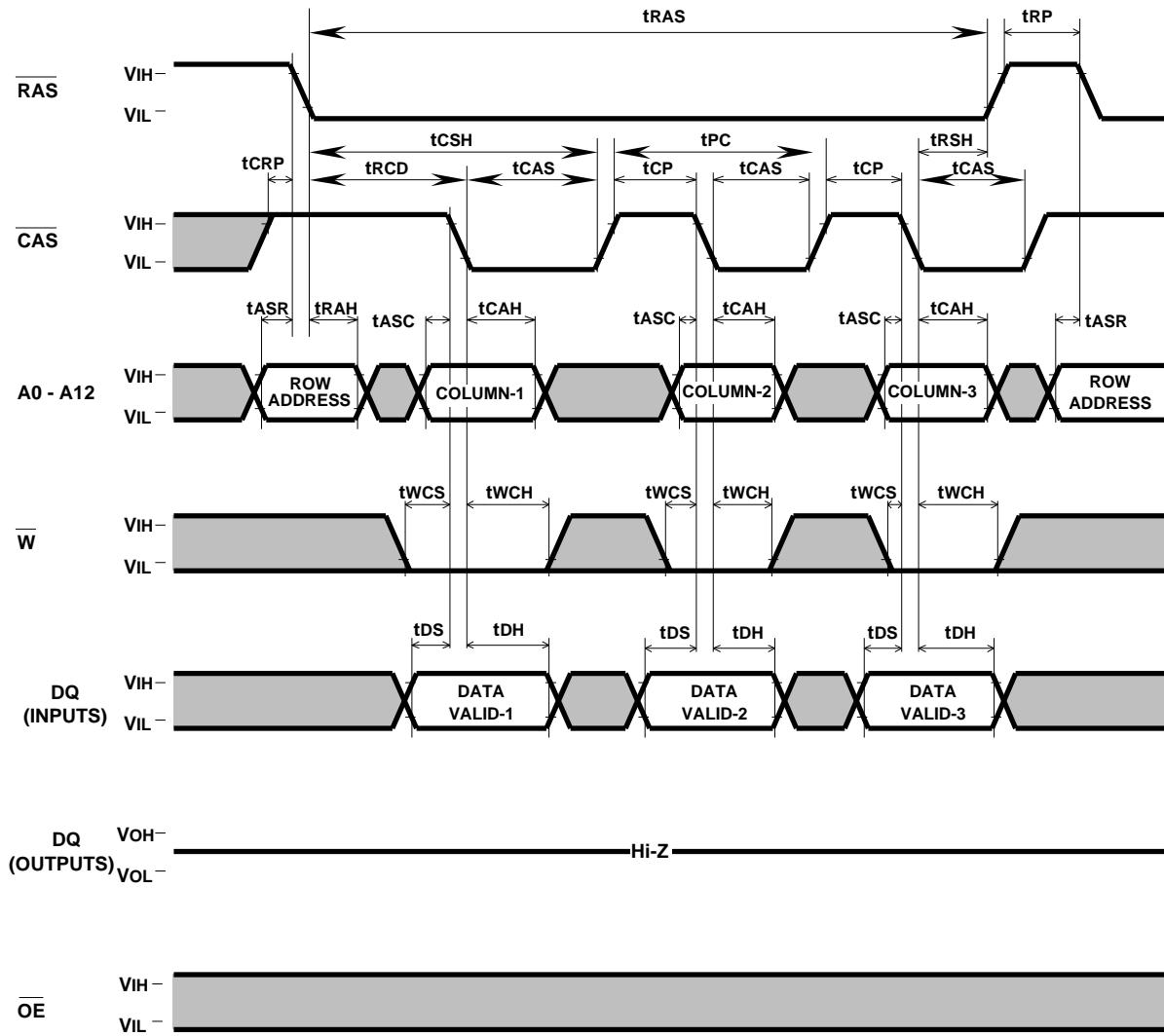
Fast Page Mode Read Cycle

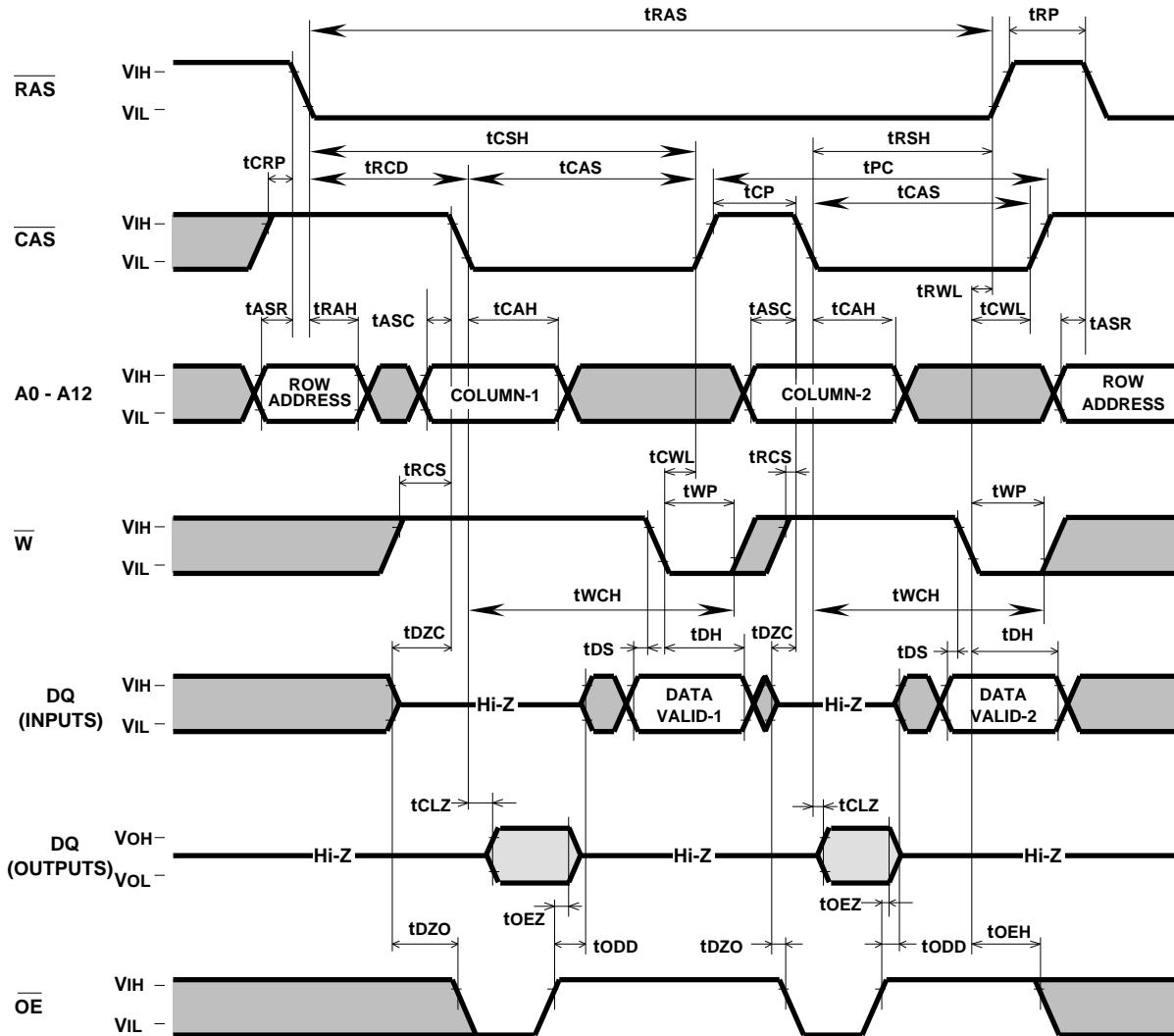


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Fast Page Mode Write Cycle (Early Write)

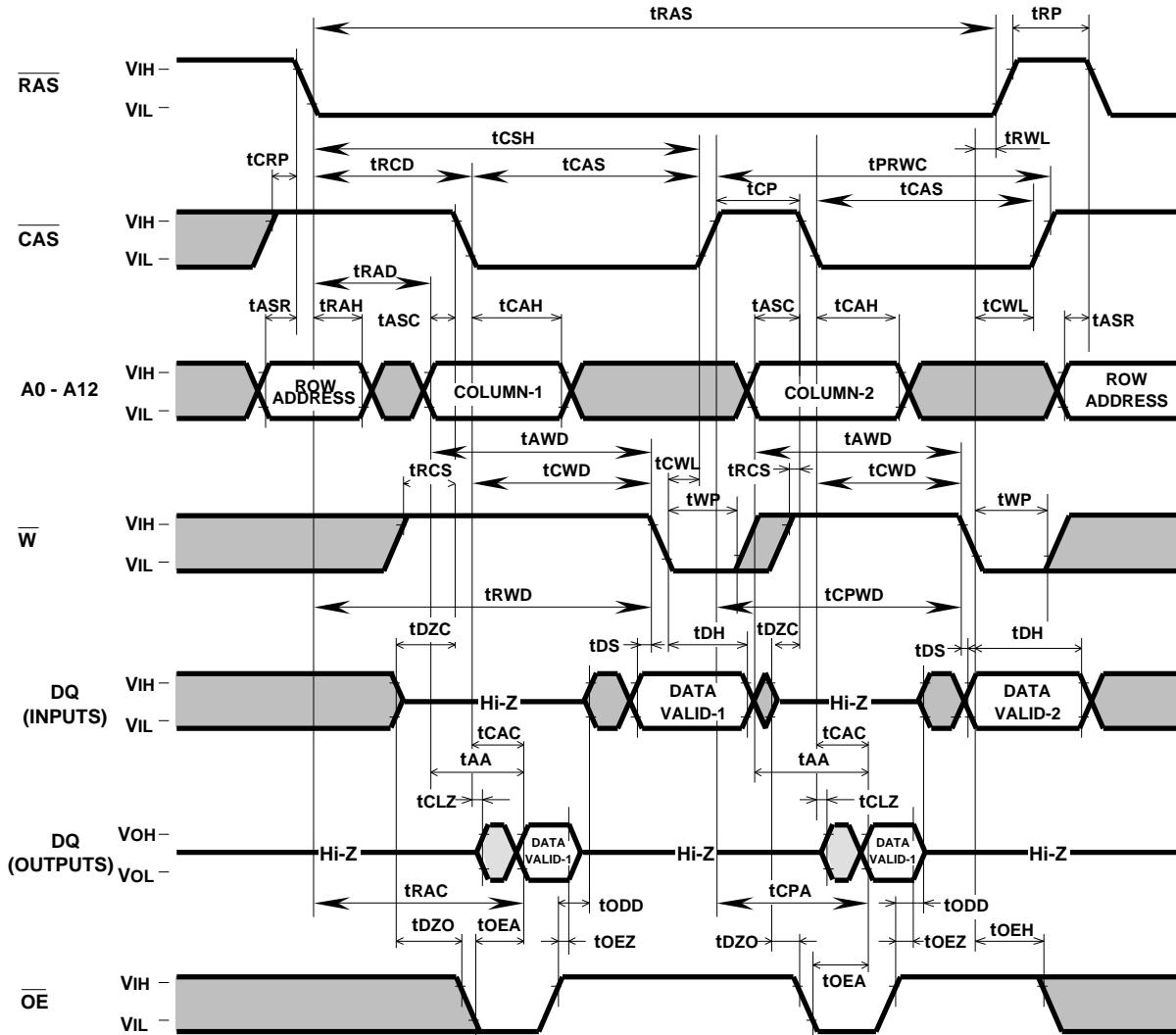
Fast-Page Mode Write Cycle (Delayed Write)

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Fast Page Mode Read-Write,Read-Modify-Write Cycle



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